AMENDMENTS TO THE SPECIFICATION

Please replace the Title beginning on page 1, line 2, as follows:

SUBSTRATE PROCESSING METHOD USING ALKALINE SOLUTION AND ACID SOLUTION ~~AND SUBSTRATE PROCESSING APPARATUS~~

Please replace the paragraph beginning at page 2, line 7, with the following rewritten paragraph:

Also in this attempt, however, the particles and the metal contaminants are removed through the etching force of hydrofluoric acid, leasing to [[such]] another problem that the quantity of etching on the surface of the substrate is disadvantageously increased (the etching thickness reaches 2.0 nm, for example).

Please replace the paragraph beginning at page 2, line 19, with the following rewritten paragraph:

In the first and second steps, particles adhering to the surface of the substrate can be physically removed due to kinetic energy resulting from collision of the droplets. In the first step, particles once liberated are prevented from experiencing re-adhesion due to repulsion of zeta potentials. Further, metal contaminants adhering to the surface of the substrate can be altered to hydroxides in the first step, to be rapidly dissolved and removed in the subsequent second step. In addition, the quantity of etching on the surface of the substrate can be suppressed dissimilarly to a case of removing particles and metal contaminants mainly by etching.

According to another aspect of the present invention, the substrate processing method includes a first step of supplying an alkaline solution ~~imparted with~~ subjected to megasonic vibrations to a surface of a substrate and a second step of supplying an acid solution to the surface of the substate after the first step.